REMARKS/ARGUMENTS

Claims 1-14 were previously pending in the application. Claims 1-14 are canceled; and new claims 15-25 are added herein. Assuming the entry of this amendment, claims 15-25 are now pending in the application. The Applicant hereby requests further examination and reconsideration of the application in view of the foregoing amendments and these remarks.

The Applicant has amended paragraph [0041] to replace "electrodes 205 and 220" with "electrodes 205 and 215" to conform with Fig. 5(b).

In paragraphs 1-2 of the office action, the Examiner objected to the drawings. In response, the Applicant submits herewith a Transmittal of Corrected Drawing(s) amending Fig. 2 to label the input port as "214" and to label the T-Cell as "201." In addition, the Applicant has amended paragraph [0009] to conform to the amendments to Fig. 2.

In paragraph 3, the Examiner objected to the disclosure. In response, the Applicant has amended paragraph [0001] as suggested by the Examiner.

In paragraphs 5-7, the Examiner objected to claims 1 and 12 under 35 U.S.C. 112, second paragraph. In paragraph 9, the Examiner rejected claims 1-6 and 10-12 under 35 U.S.C. 102(e) as being anticipated by Kaitila. In paragraph 20, the Examiner rejected claims 7-9 and 13-14 under 35 U.S.C. 103(a) as being unpatentable over Kaitila in view of Fischer. Since claims 1-14 have been canceled, the Applicant submits that all of these rejections are moot.

Support for new claims 15-25 is found as follows:

New Claim	Support
15	Fig. 5(b) and Paragraph [0041]
16	Paragraph [0041]
17	Fig. 7 and Paragraph [0043]
18	Fig. 5(b) and Paragraph [0041]
19	Fig. 7 and Paragraph [0043]
20	Fig. 7 and Paragraph [0043]
21	Fig. 7 and Paragraph [0043]
22	Fig. 5(a) and Paragraph [0040]
23	Fig. 5(b) and Paragraph [0041]
24	Fig. 5(b) and Paragraph [0041]
25	Fig. 7 and Paragraph [0043]

For the following reasons, the Applicant submits that all of the now-pending claims are allowable over the cited references.

New Claim 15

New claim 15 is directed to an integrated structure having a piezoelectronic device, the integrated structure comprising (i) a substrate and (ii) a piezoelectric layer and one or more conducting elements integral to the piezoelectronic device. The piezoelectric layer is supported on the substrate, such that the piezoelectric layer spans a cavity in the substrate to form a suspended membrane portion of the piezoelectric layer, and one or more conducting elements integral to the piezoelectronic device are mounted on the suspended membrane portion of the piezoelectric layer.

The cited references, whether considered alone or in combination, fail to teach such a combination of features. For example, none of the cited references teaches or even suggests a piezoelectronic device having a piezoelectric layer supported on a substrate, such that the piezoelectric layer spans a cavity in the substrate to form a suspended membrane portion of the piezoelectric layer upon which one or more conducting elements of the piezoelectronic device are mounted.

The Applicant submits therefore that claim 15 is allowable over the cited references. Since new claims 16-20 depend variously from claim 15, it is further submitted that those claims are also allowable over the cited references.

New Claim 21

New claim 21 is directed to an integrated structure having an electronic device, the integrated structure comprising a substrate, a layer supported on the substrate, one or more elements integral to the electronic device, and one or more conducting leads. The layer spans a cavity in the substrate to form a suspended membrane portion of the layer, and the one or more elements are mounted on the suspended membrane portion of the layer. The one or more conducting leads run along the suspended membrane portion of the layer from one or more corresponding elements of the electronic device towards an edge of the layer. The integrated structure is mounted in an edge-on fashion within a recess of a package having one or more bonding leads mated to the one or more conducting leads of the electronic device.

The cited references, whether considered alone or in combination, fail to teach such a combination of features. For example, none of the cited references teaches or even suggests an integrated structure having an electronic device and mounted in an edge-on fashion within a recess of a package having one or more bonding leads mated to one or more conducting leads of the electronic device.

The Applicant submits therefore that claim 21 is allowable over the cited references. Since new claims 22-25 depend variously from claim 21, it is further submitted that those claims are also allowable over the cited references.

In view of the above amendments and remarks, the Applicant believes that the now-pending claims are in condition for allowance. Therefore, the Applicant believes that the entire application is now in condition for allowance, and early and favorable action is respectfully solicited.

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Respectfully submitted,

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